LNA2903L (LN66A)

GaAs Infrared Light Emitting Diode

For remote control systems

■ Features

- High-power output, high-efficiency: $I_e = 9 \text{ mW/sr (min.)}$
- Emitted light spectrum suited for silicon photodetectors
- Good radiant power output linearity with respect to input current
- Wide directivity: $\theta = 20^{\circ}$ (typ.)
- Transparent epoxy resin package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	160	mW	
Forward current	I_{F}	100	mA	
Pulse forward current *	I_{FP}	1.5	A	
Reverse voltage	V_R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-40 to +100	°C	

Note) *: f = 100 Hz, Duty cycle = 0.1%

■ Electrical-Optical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Radiant power	P _O	$I_F = 50 \text{ mA}$		12.0		mW
Reverse current	I_R	$V_R = 3 V$			10	μΑ
Forward voltage	V _F	$I_F = 100 \text{ mA}$		1.4	1.6	V
Pulse forward voltage *1	V _{FP}	$I_{FP} = 1.0 A$			3.0	V
Center radiant intensity *2	I _e	$I_F = 50 \text{ mA}$	9.0			mW/sr
Terminal capacitance	C _t	$V_R = 0 \text{ V, } f = 1 \text{ MHz}$		35		pF
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 50 \text{ mA}$		950		nm
Spectral half band width	Δλ	$I_F = 50 \text{ mA}$		50		nm
Half-power angle	θ	The angle when the radiant power is halved.		20		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

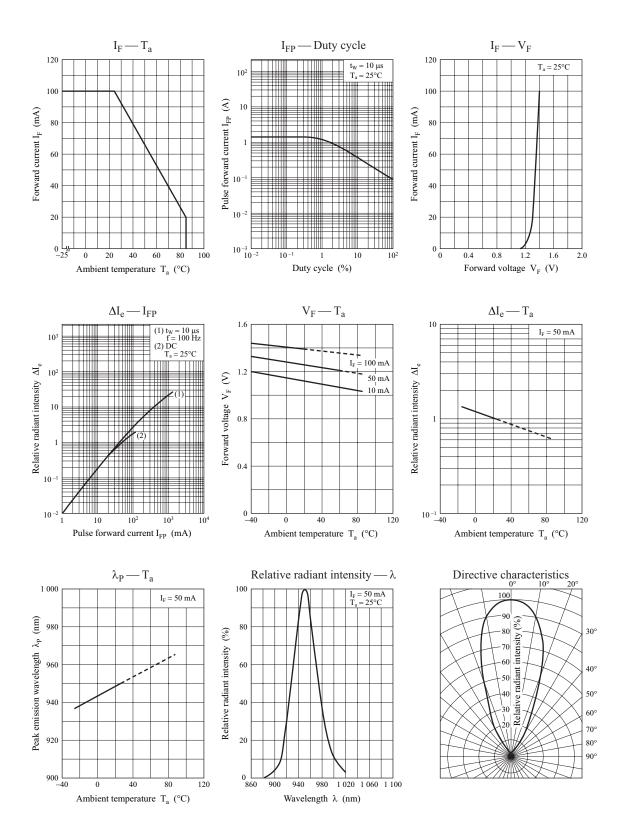
2. Cutoff frequency: 1 MHz

$$f_C: 10 \times \log \frac{P_O \text{ at } f = f_C}{P_O \text{ at } f = 50 \text{ kHz}} = -3$$

- 3. *1: f = 100 Hz, Duty cycle = 0.1%
 - *2: Rank classification

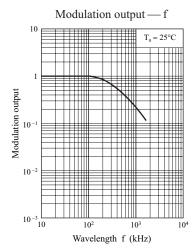
Rank	No-rank	S
I _e (mW/sr)	9.0 ≤	11.0 ≤

Note) The part number in the parenthesis shows conventional part number.



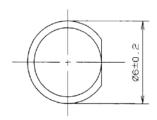
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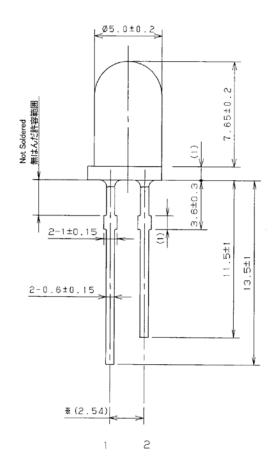
Panasonic LNA2903L

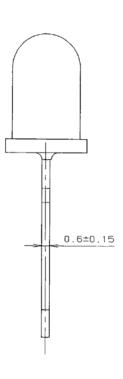


■ Package (Unit: mm)

LEXLTN2S0004







- Pin name
 - 1: Anode
 - 2: Cathode

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